



PATENT  
0152-0551P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: ARIYASU, Hideyuki et al Conf.: 7701  
Appl. No.: 09/773,627 Group: 1773  
Filed: February 2, 2001 Examiner: Kruer, Kevin  
For: THERMOPLASTIC RESIN INTEGRATED  
STRUCTURE

*B/#7*  
*107/09/03*  
*AS*  
**RECEIVED**  
**JUL 02 2003**  
**TC 1700**

REPLY UNDER 37 C.F.R. § 1.111

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

June 30, 2003

Sir:

In reply to the Office Action dated March 31, 2003, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

This reply includes claim amendments and remarks.

The amendments presented herein comply with the "Revised Amendment Format" as set forth in the Official Gazette Notice dated February 25, 2003. In accordance with the Notice, the provisions of 37 C.F.R. § 1.121(a)-(d) are waived.